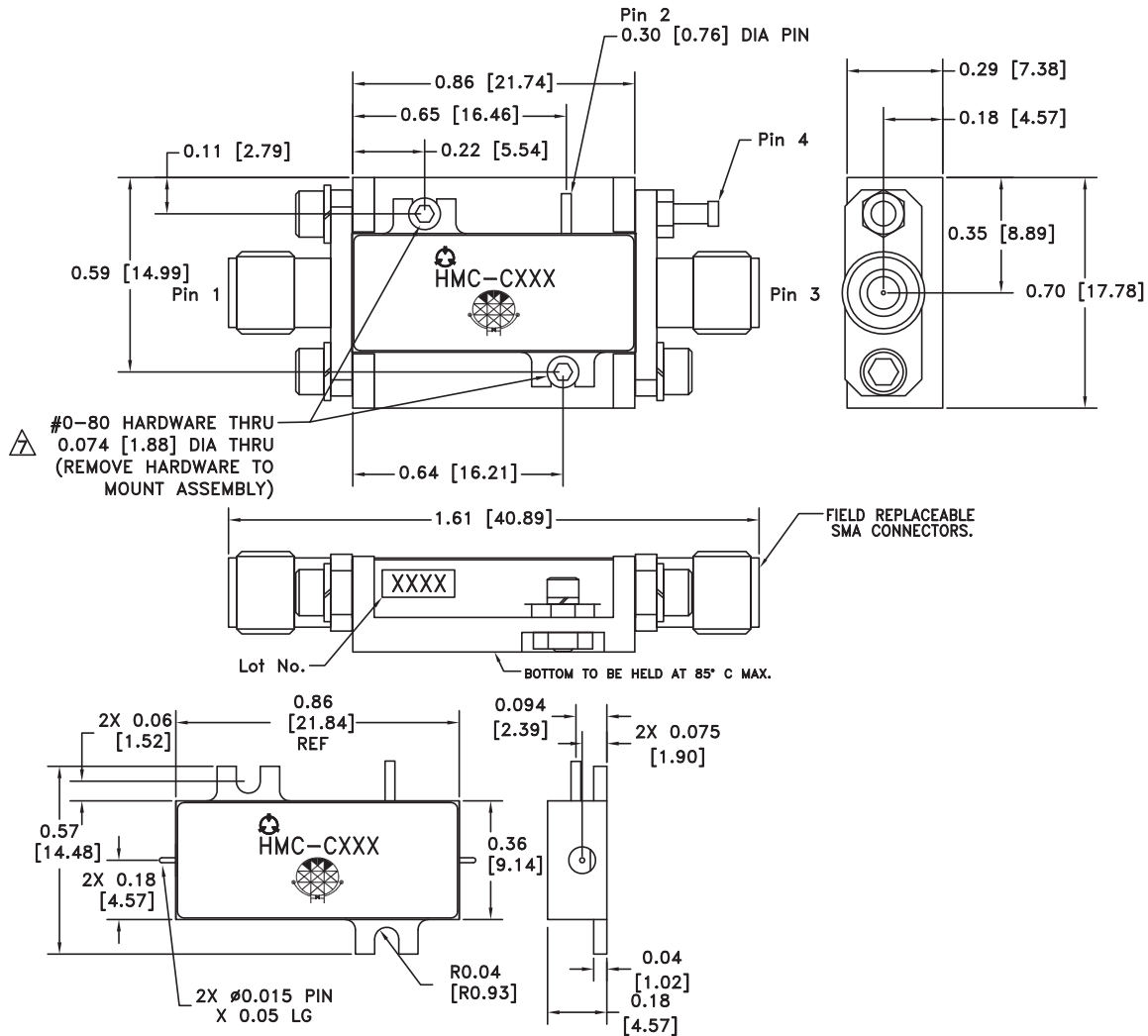


## C-3 – CONNECTORIZED HERMETIC MODULE

C-3 Package Outline Drawing

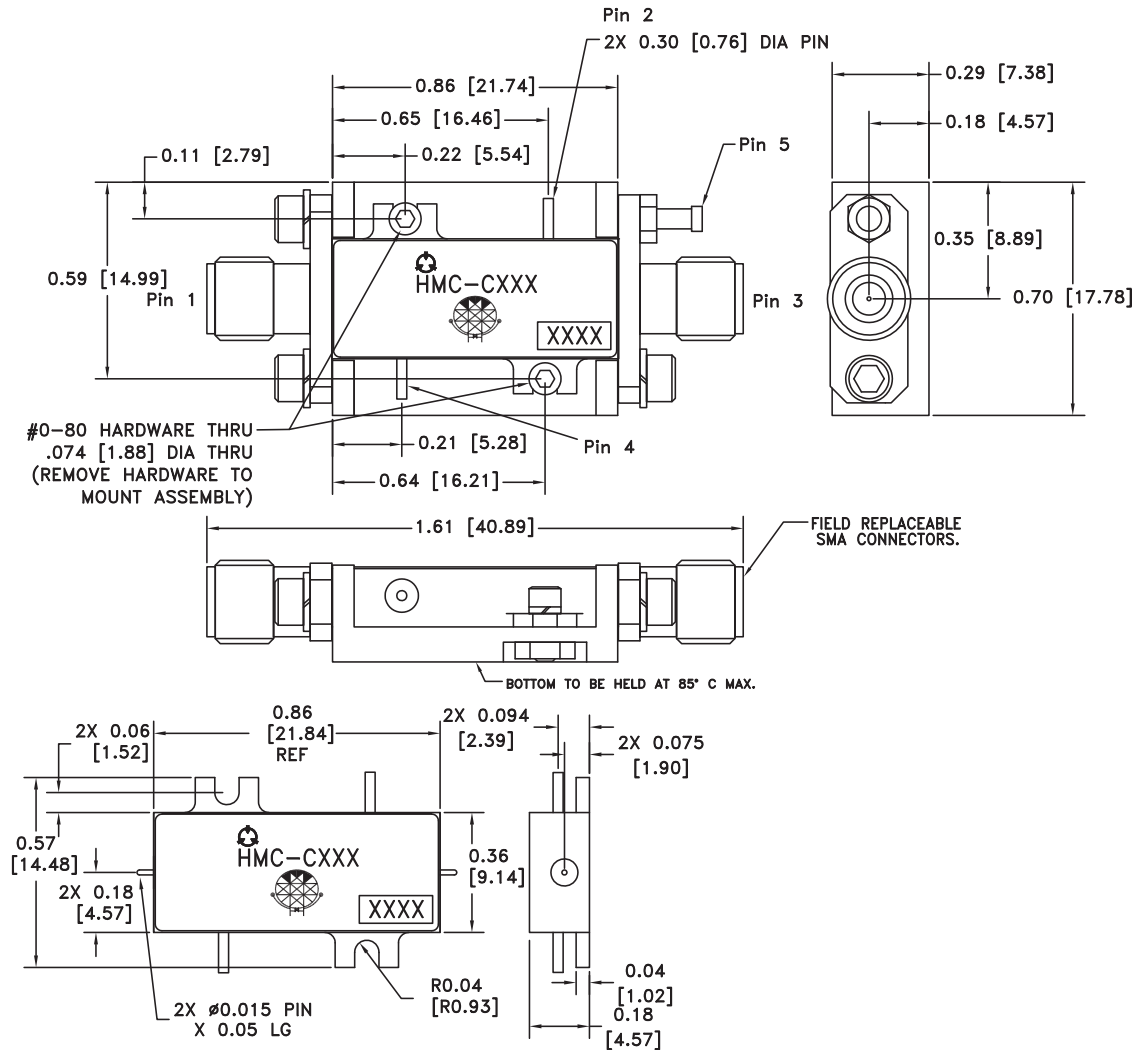


**NOTES:**

1. PACKAGE, LEADS, COVER MATERIAL: KOVAR™
  2. SPACER MATERIAL: ALUMINUM
  3. PLATING: ELECTROLYTIC GOLD 50 MICROINCHES MIN., OVER ELECTROLYTIC NICKEL 75 MICROINCHES MIN.
  4. ALL DIMENSIONS ARE IN INCHES [MILLIMETERS].
  5. TOLERANCES  $\pm$ 0.005 [0.13] UNLESS OTHERWISE SPECIFIED.
  6. FIELD REPLACEABLE SMA CONNECTORS.
- TENSOLITE 5602 - 5CCSF OR EQUIVALENT.
- $\triangle$  TO MOUNT MODULE TO SYSTEM PLATFORM REPLACE 0-80 HARDWARE WITH DESIRED MOUNTING SCREWS.

## C-3B – CONNECTORIZED HERMETIC MODULE

### C-3B Package Outline Drawing



#### NOTES:

1. PACKAGE, LEADS, COVER MATERIAL: KOVAR™
  2. SPACER MATERIAL: ALUMINUM
  3. PLATING: ELECTROLYTIC GOLD 50 MICROINCHES MIN., OVER ELECTROLYTIC NICKEL 75 MICROINCHES MIN.
  4. ALL DIMENSIONS ARE IN INCHES [MILLIMETERS].
  5. TOLERANCES ±.005 [0.13] UNLESS OTHERWISE SPECIFIED.
  6. FIELD REPLACEABLE SMA CONNECTORS.  
TENSOLITE 5602 - 5CCSF OR EQUIVALENT.
- △ TO MOUNT MODULE TO SYSTEM PLATFORM REPLACE 0-80 HARDWARE WITH DESIRED MOUNTING SCREWS.

